

IEEE 1394-1995 and P1394a Compliant General-Purpose Link-Layer Controller for Computer Peripherals and Consumer Audio/Video Electronics

FEATURES

- Compliant With IEEE 1394-1995 Standards and 1394a-2000 Supplement for High Performance Serial Bus¹
- Supports Transfer Rates of 400, 200, or 100 Mbps
- Compatible With Texas Instruments Physical Layer Controllers (Phys)
- Supports the Texas Instruments Bus Holder Galvanic Isolation Barrier
- Glueless Interface to 68000 and ColdFire Microcontrollers/Microprocessors
- Supports ColdFire Burst Transfers
- 2-Kbyte General Receive FIFO (GRF) Accessed Through Microcontroller Interface Supports Asynchronous and Isochronous Receive.
- 2-Kbyte Asynchronous Transmit FIFO (ATF) Accessed Through Microcontroller Interface Supports Asynchronous Transmissions.
- Programmable Microcontroller Interface With 8-Bit or 16-Bit Data Bus, Multiple Modes of Operation Including Burst Mode, and Clock Frequency to 60 MHz
- 8-Bit or 16-Bit Data-Mover Port (DM Port) Supports Isochronous, Asynchronous, and Asynchronous Streaming Transmit/Receive From an Unbuffered Port at a Clock Frequency of 25 MHz.
- Backward Compatible With All TSB12LV31(GPLynx) Microcontroller and Data-Mover Functionality in Hardware
- Two-Channel Support for Isochronous Receive to Unbuffered 8/16 Data-Mover Port
- Four-Channel Support for Isochronous Transmit From Unbuffered 8/16 Bit Data-Mover Port
- Single 3.3-V Supply Operation With 5-V Tolerance Using 5-V Bias Terminals
- High Performance 100-Pin PZ Package

NOTE: Implements technology covered by one or more patents of Apple Computer, Incorporated and SGS Thomson, Limited.

DESCRIPTION

The TSB12LV32 (GP2Lynx) is a high-performance general-purpose IEEE 1394a-2000 link-layer controller (LLC) with the capability of transferring data between the 1394 Phy-link interface, an external host controller, and an external device connected to the data-mover port (local bus interface). The 1394 Phy-link interface provides the connection to a 1394 physical layer device and is supported by the LLC. The LLC provides the control for transmitting and receiving 1394 packet data between the microcontroller interface and the Phy-link interface via internal 2-Kbyte FIFOs at rates up to 400 Mbps. The TSB12LV32 transmits and receives correctly formatted 1394 packets, generates and detects the 1394 cycle start packets, communicates transaction layer transmit requests to the Phy, and generates and inspects the 32-bit cyclic redundancy check (CRC).

The TSB12LV32 is capable of being 1394 cycle master (CM), 1394 bus manager, 1394 isochronous resource manager (IRM) if additional control status registers (CSRs) are added via the external host controller, and supports reception of 1394 isochronous data on two channels and transmission of 1394 isochronous data on four channels.

The TSB12LV32 supports a direct interface to many microprocessors/microcontrollers by including programmable endian swapping. TSB12LV32 has a generic 16-/8-bit host bus interface which includes support for a ColdFireE microcontroller mode at rates up to 60 MHz. The microcontroller interface can operate in byte or word (16 bit) accesses.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

The data-mover block in GP2Lynx handles the external memory interface of large data blocks. This local bus interface can be configured either to transmit or receive data packets. The packets can be either asynchronous, isochronous, or asynchronous streaming data packets. The data-mover (DM) port can receive any type of packet, but it can only transmit one type of packet at a time: isochronous data packets, asynchronous data packets, or asynchronous stream data packets.

The internal FIFO is separated into an asynchronous transmit FIFO (ATF) and a general receive FIFO (GRF), each of 520 quadlets (2 Kbytes). Asynchronous and/or isochronous receive packets can be routed to either the DM port or the GRF via the receiver routing control logic. Asynchronous data packets or asynchronous stream data packets can be transmitted from the DM port or the internal FIFO: ATF. If there is contention the ATF has priority and is transmitted first. Isochronous packets can only be transmitted by the data-mover port.

The LLC also provides the capability to receive status information from the physical layer device and to access the physical layer control and status registers by the application software.

NOTE:

This product is for high-volume applications only. For a complete datasheet or more information contact support@ti.com.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TSB12LV32IPZG4	OBSOLETE	LQFP	PZ	100		TBD	Call TI	Call TI	
TSB12LV32PZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	
TSB12LV32PZG4	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TSB12LV32 :

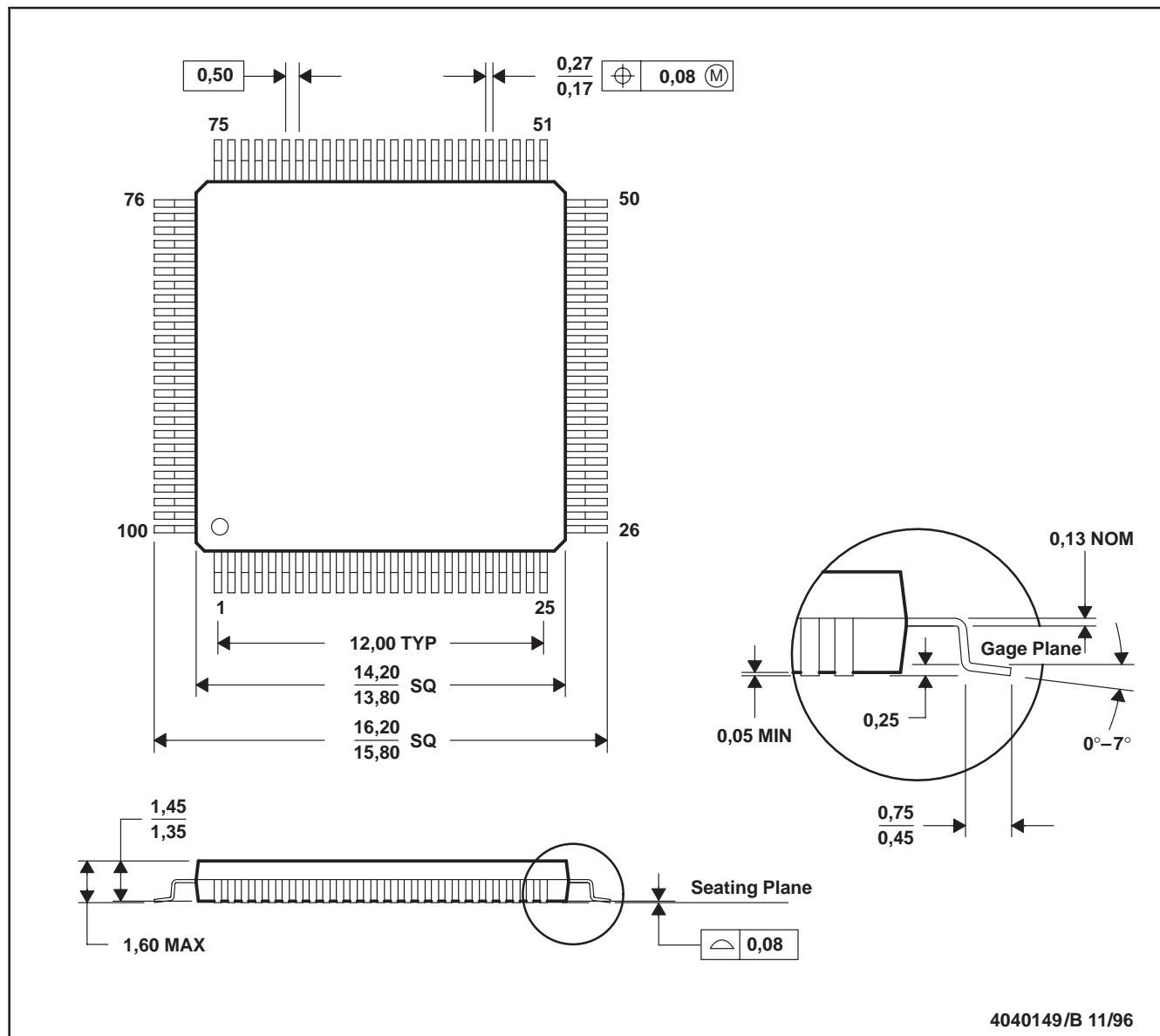
- Enhanced Product: [TSB12LV32-EP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

PZ (S-PQFP-G100)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-026

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com